12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260826001.2	PCN Issued	September 18, 2026
Qualification of RFAB and MIHO8 as additional Fab site options using the LBC7 qualified process technology for select devices		Sample request deadline:	November 17, 2026
		Estimated 1st ship date:	March 17, 2027
***Sample requests received after** November 17, 2026* **will not be supported.**			

Change Type(s)	Packing/Shipping/Labeling Wafer Fab Site Wafer Fab Material Wafer Fab Process
ZVEI ID	SEM-PW-13, SEM-PW-02, SEM-PW-07, SEM-PW-03, SEM-PW-05

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB and MIHO8 using the LBC7 qualified process technology for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
FFAB	LBC7	200mm	**RFAB**	LBC7	**300mm**
FFAB	LBC7	200mm	**MIHO8**	LBC7	200mm

	FFAB	**RFAB**	**MIHO**
Metallization material	Al (0.5% cu)	Ti, TiN, AlCu	Ti, TiN, AlCu
Dielectric Material	PMD: BPSG, ILO: Silicon Oxide	SiO2, BPSG, HDP Oxide, TEOS	Si3N4 SiO2
Final Wafer Thickness	191µm	152µm	152µm

Qual details are provided in the Qual Data Section.

Reason for Change:	Supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• These devices include new die based on a new schematic in a new process flow.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated

environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
MIHO8	**MH8**	**JPN**	**Ibaraki**
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label):

Products Affected:			
TPS70925QDBVRQ1	TPS70930QDBVRQ1	TPS70936QDBVRQ1	TPS70950QDBVRQ1
TPS70928QDBVRQ1	TPS70933QDBVRQ1		

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

TPS709DBV-Q1 CSF project @ TIPI - Wire Diameter Change Qualification
Approve Date 06-August -2026

Product Attributes

Attributes	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	QBS Package Reference: TLV1805QDBVRQ1	QBS Process Reference: TPS652510QRHARQ1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Package Reference: PSN74LVC2G17DBVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management	Signal Chain	Power Management	Power Management	Power Management	Logic
Wafer Fab Supplier	RFAB	MH8	RFAB	MH8	RFAB	RFAB	RFAB	MH8	RFAB
Assembly Site	PHI	PHI	PHI	PHI	PHI	CLARK-AT	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	SOT	QFN	SOT	SOT	SOT
Package Designator	DBV	DBV	DBV	DBV	DBV	RHA	DBV	DBV	DBV
Pin Count	5	5	5	5	6	40	5	5	6

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TPS70930QDBVRM3Q1 is qualified at MSL1 260C
- Qual Device TPS70930QDBVRM3Q1 is qualified at MSL1 260C
- Qual Device TPS70933QDBVRM3Q1 is qualified at MSL1 260C
- Qual Device TPS70933QDBVRM3Q1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	QBS Package Reference: TLV1805QDBVRQ1	QBS Process Reference: TPS652510QRHARQ1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Package Reference: PSN74LVC2G17DBVRQ1
Test Group A - Accelerated Environment Stress Tests																
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	1/All/0	1/All/1[1]	-	-	3/All/0	-	-	-	1/All/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	3/231/0	-	-	-	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-	-	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	-	-	-	-	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	-	-	-	-	-	-	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	1/5/0	-	-	1/5/0	-	-	-	1/5/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70930QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	Qual Device: TPS70933QDBVRM3Q1	QBS Package Reference: TLV1805QDBVRQ1	QBS Process Reference: TPS652510QRHARQ1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Process, Product Reference: TPS70930QDBVRM3Q1	QBS Package Reference: PSN74LVC2G17DBVRQ1
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	-	-	-	-	-	-	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/135/0	-	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests																
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	1/77/0	1/87/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	3/2400/0	-	-	-
Test Group C - Package Assembly Integrity Tests																
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	-	-	3/90/0	-	-	-	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	-	-	3/90/0	-	-	-	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	-	1/15/0	-	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	1/10/0	-	-	3/30/0	-	-	-	1/10/0
Test Group D - Die Fabrication Reliability Tests																
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests																
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	Corner pins	750 Volts	-	-	-	-	-	-	-	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	-	-	-	-	1/3/0	1/3/0	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	3/90/0	3/90/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : ACIuHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2604-104

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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